



ASM International N.V.

ASM International N.V. to Host 45nm Interconnect Technology Seminar

BILTHOVEN, the Netherlands, June 3, 2005 – ASM International N.V. (NASDAQ: ASMI and Euronext Amsterdam: ASM) will host a technical seminar for 45nm interconnect technology in the evening of June 7, 2005 at the Hyatt Regency at the San Francisco Airport in Burlingame, CA.

The seminar is held in conjunction with the IEEE International Interconnect Technology Conference (IITC). Subjects covered by ASM will be: “*PECVD Technology for 45nm and Beyond*”, “*Ru/WNC Bilayer Barrier for Cu Interconnect*”, and “*Planar Copper for Advanced Interconnects*”, and a guest speaker from the industry will discuss “*Material and Process Challenges for Mechanically Reliable Cu/ULK Interconnect Integration*”. Additionally, Ivo Raaijmakers, ASM’s Chief Technology Officer will present ASM’s perspective on interconnect scaling.

Those interested in attending this seminar should contact Carolyn Olsen at ASM America Inc. +1 408 451 0830 or carolyn.olsen@asm.com.

About ASM

ASM International N.V., headquartered in Bilthoven, the Netherlands, is a global company servicing one of the most important and demanding industries in the world. The Company possesses a strong technology base, state-of-the-art manufacturing facilities, a competent and qualified workforce and a highly trained, strategically distributed support network. ASM International and its subsidiaries design and manufacture equipment and materials used to produce semiconductor devices. ASM International and its subsidiaries provide production solutions for wafer processing (Front-end segment) as well as assembly and packaging (Back-end segment) through facilities in the United States, Europe, Japan and Asia. ASM International's common stock trades on NASDAQ (symbol ASMI) and the Euronext Amsterdam Stock Exchange (symbol ASM). For more information, visit ASMI's web site at www.asm.com